

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>	 STMicroelectronics International N.V
<b>1.2 PCN No.</b>	EMBEDDED PROCESSING/26/16067
<b>1.3 Title of PCN</b>	ST Shenzhen (China) assembly site and HHgrace (China) Diffusion site additional source for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 24x24 packages.
<b>1.4 Product Category</b>	STM32H742x, STM32H743x, STM32H750x and STM32H753x
<b>1.5 Issue date</b>	2026-04-21

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	_____
<b>2.1.2 Phone</b>	_____
<b>2.1.3 Email</b>	_____
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	_____
<b>2.1.2 Marketing Manager</b>	_____
<b>2.1.3 Quality Manager</b>	_____

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China), HHGrace (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Current assembly sites (depending on package size) with Crolles Diffusion source: - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Gold wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire ,  You may refer to 16067_Additional information.pdf document for further details.	Current assembly sites (depending on package size) with Crolles Diffusion source: - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Gold wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire ,  Additional assembly site with HHGrace Diffusion Source for extended capacity: - ST Shenzhen (China) Copper Alloy wire .
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No Impact on Form, Fit or Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Change is visible on the marking - Back-End Assembly Site code: • GK : ST Shenzhen (China) New Assembly site • 7B : AMKOR ATP (Philippines) • AA : ASE KaoHsiung (Taiwan)  - Diffusion plant code WX: • VQ : ST Crolles 300 (France) • Y5 : HHGrace WuXi (China) Fab 7 New Diffusion site • 2E : HHGrace WuXi (China) Fab 9 New Diffusion site  Please refer to PCN 16067_Additional information.pdf document for further details.
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7. Timing / schedule	
7.1 Date of qualification results	2026-06-15
7.2 Intended start of delivery	2026-06-22
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-04-21

9. Attachments (additional documentations)
16067 Public product.pdf 16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf 16067 Additional information.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H750ZBT6	
	STM32H753ZIT6	

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## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** ST Shenzhen (China) assembly site and HHgrace (China) Diffusion site additional source for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 24x24 packages.

**PCN Reference :** EMBEDDED PROCESSING/26/16067

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H743ZGT6	STM32H743IGT6	STM32H750IBT6
STM32H750ZBT6	STM32H742ZIT6	STM32H743ZIT6
STM32H743ZIT6TR	STM32H743IIT6	STM32H742ZGT6
STM32H753ZIT6	STM32H753IIT6	STM32H742IIT6

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**PRODUCT/PROCESS  
CHANGE NOTIFICATION  
PCN16067 – Additional information**

**ST Shenzhen (China) assembly site and HHgrace (China)  
Diffusion site additional source for STM32H74x and STM32H75x  
listed products in LQFP 20x20 and LQFP 24x24 packages.**

**MRDF – General Purpose and Automotive Microcontrollers (GPAM)**

**What are the changes?**

- STM32H75x/74x products have been transferred to ST Shenzhen (China) and to HHGrace WuXi (China) FAB. We are adding TQFP20x20 and TQFP24x24 in ST Shenzhen only for HHGrace source. HHGrace source was already qualified through PCN15272.
- The design database remains the same. No change in the silicon version however in a second step a fix will be added to improve the yield at Electrical Wafer Sort.

**How can the change be seen?**

**Table 1: Front-End Diffusion / Back-End Sites**

	Current condition	New condition	
Front-End Diffusion site	ST Crolles 300 (France)	HHGrace WuXi (China)	
		<b>Fab 7</b>	<b>Fab 9</b>
Die revision Marking <b>R</b>	<b>“V”</b>	<b>“2”</b>	<b>“3”</b>
Diffusion plant code <b>WX</b>	<b>“VQ”</b>	<b>“Y5”</b>	<b>“2E”</b>

	Existing Back-end		Added Back-End Site
Assembly sites	ASE KaoHsiung (Taiwan)	AMKOR ATP (Philippines)	ST Shenzhen (China)
Assembly plant code <b>PP</b>	<b>“AA”</b>	<b>“7B”</b>	<b>“GK”</b>



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**Table 2: Marking Example** with Commercial product

STM32H742ZIT6 LQFP 144L 20X20 package	STM32H743IIT6 LQFP 176L 24x24 package

- **WX** Diffusion plant code
- **PP** Assembly Plant code
- **R - Die Revision changes** from (ST Crolles CR300) to (HHGrace Wuxi)
- **Y WW** : Year Week (manufacturing date)

Please refer to product [DataSheet](#) or Technical Note **TN1433** for package marking details.

**Table 3 : Back-End assembly Sites for LQFP 144L 20x20 packages**

LQFP 144L 20X20	Existing back-End assembly lines		Added line
<b>Assembly Plant</b>	AMKOR ATP (Philippine)	ASE Kaohsiung (Taiwan)	ST Shenzhen (China)
<b>Diffusion Fab</b>	Crolles CRPF (France)		HHG Fab7      Fab9
<b>Bill Of Material (BOM)</b>			
<b>Molding Compound</b> <sup>(2)</sup>	G631SHQ	G631SH	CEL-9240ZHF
<b>Die attach Glue</b>	Evertch AP4200	D/A Ablestik 3230	HITACHI EN4900G
<b>Bonding Wire</b>	Gold 0.8 Mils	CuPd 0.8 Mils	Copper Alloy 0.8 Mils
<b>Leadframe</b>	Copper, post-plated		
<b>Leadfinishing</b> <sup>(1)</sup>	Pure Tin (e3)		
<b>Marking composition</b>	2D Marking		



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**Table 4 : Back-End assembly Sites for LQFP 176L 24x24 packages**

<b>LQFP 176L 24x24</b>	<b>Existing plant</b>		<b>Added lines</b>	
<b>Assembly Plant</b>	<b>ASE Kaohsiung (Taiwan)</b>		<b>ST Shenzhen (China)</b>	
<b>Diffusion Fab</b>	<b>Crolles CRPF (France)</b>		<b>HHG</b>	
			<b>Fab7</b>	<b>Fab9</b>
<b>Bill Of Material (BOM)</b>				
<b>Molding Compound <sup>(2)</sup></b>	G631SH		CEL-9240ZHF	
<b>Die attach Glue</b>	YIZTECH 8143	HITACHI EN4900G	ABLESTIK 8303A	
<b>Bonding Wire</b>	Gold 0.8 Mils	CuPd 0.8 Mils	Copper Alloy 0.8 mils	
<b>Leadframe</b>	Copper, post-plated			
<b>Leadfinishing <sup>(1)</sup></b>	Pure Tin (e3)			
<b>Marking composition</b>	w/o 2D		2D marking	

<sup>(1)</sup> Lead color and surface finishing may slightly vary depending on lead finishing.

<sup>(2)</sup> Package darkness or chromaticity may change depending on molding compound.

Pin1 identifier may change in terms of size and positioning however remaining near pin1's edge.  
Marking position and size may be different upon assembly site, without any loss of information.



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## How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu).
- insert the PCN number "**PCN16067**" into the NPO Electronic Sheet/**Regional Sheet**.
- request sample(s) through Notice tool, indicating a single Commercial Product for each request.

Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

%: 0 Sample Type: Sample Non Std Type

Closing Type: Sample Std Type  
Sample Non Std Type  
Sample Non Std w Spl Tests

Lab Sheet:

SO | NPO Sample

Header  
SO Nr: 0018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J  
PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:  
Notes: Status: 01 All Items pending, etc Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I Nr	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust:  
PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 0800367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: Lab Sheet:

PCN 16067



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**MDRF-GPAM-RER2506 for PCN16067**

**ST Shenzhen (China) additional source for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 24x24 packages**

**Reliability Evaluation Plan**

**10<sup>th</sup> March, 2026**

**MDRF GPAM Quality & Reliability Department**



# MDRF-GPAM-RER2506

## ST Shenzhen (China) LQFP 20x20 and LQFP 24x24 packages

### Package Test Vehicles

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process Plant	Number of Reliability Lots
LQFP	LQFP24x24	176L	1T*413	RSST M10	3
	LQFP20x20	144L	1A*450	HHG M40	1
	LQFP24x24	176L	1T*450	HHG M40	1

**Reliability strategy:**

- For line qualification, reliability will be performed on 3 lots from representative test vehicles of STM32F40x.
- Reliability will be performed on 2 lots from representative test vehicles of STM32H74x & STM32H75x listed products, to cover HHG M40 technology.
- Refer to details in above and next tables.





# MDRF-GPAM-RER2506 ST Shenzhen (China) LQFP 20x20 and LQFP 24x24 packages Package Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Lot qty
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3  J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3  Convection reflow: 3 passes	3 passes MSL3	231	5
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h 168h for monitoring	77	5
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy 1000cy for monitoring	77	5
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h 1500h for monitoring	77	5
HTSL	High Temperature Storage Life JESD22 A103	150°C- no bias	1000h 1500h for monitoring	77	5
Construction analysis	ST internal specifications	Construction analysis including Ball shear, pull test	NA	50	3
ESD	ESD Charge Device Model JEDEC JS-002	Aligned with device datasheet	Aligned with device datasheet	3	3

(\*) tests performed after preconditioning



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